

General Description

The AO4420A uses advanced trench technology to provide excellent $R_{DS(ON)}$ shoot-through immunity and body diode characteristics. This device is suitable for use as a synchronous switch in PWM applications.

Features

V_{DS} (V) = 30V ,

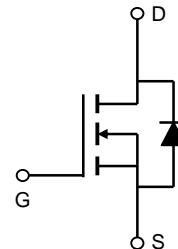
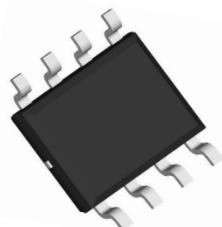
I_D = 13.7A (V_{GS} = 10V)

$R_{DS(ON)}$ < 10.5mΩ (V_{GS} = 10V)

$R_{DS(ON)}$ < 12mΩ (V_{GS} = 4.5V)



SOIC-8



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current ^A F	I_D	13.7	A
$T_A=70^\circ\text{C}$		9.7	
Pulsed Drain Current ^B	I_{DM}	60	
Avalanche Current ^B	I_{AR}	20	A
Repetitive avalanche energy $L=0.3\text{mH}$ ^B	E_{AR}	60	mJ
Power Dissipation	P_D	3.1	W
$T_A=70^\circ\text{C}$		2	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	28	40	°C/W
Steady-State		54	75	°C/W
Maximum Junction-to-Lead ^C	$R_{\theta JL}$	21	30	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=24\text{V}, V_{GS}=0\text{V}$		0.004	1	μA
		$T_J=55^\circ\text{C}$			5	
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm 12\text{V}$			100	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.6	1.1	2	V
$I_{\text{D(ON)}}$	On state drain current	$V_{GS}=4.5\text{V}, V_{DS}=5\text{V}$	40			A
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=13.7\text{A}$		8.3	10.5	$\text{m}\Omega$
		$T_J=125^\circ\text{C}$		12.5	15	
g_{FS}	Forward Transconductance	$V_{DS}=5\text{V}, I_D=13.7\text{A}$	30	37		S
V_{SD}	Diode Forward Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$		0.76	1	V
I_S	Maximum Body-Diode Continuous Current				5	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=15\text{V}, f=1\text{MHz}$		3656	4050	pF
C_{oss}	Output Capacitance			256		pF
C_{rss}	Reverse Transfer Capacitance			168		pF
R_g	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		0.86	1.1	Ω
SWITCHING PARAMETERS						
$Q_g(4.5\text{V})$	Total Gate Charge	$V_{GS}=4.5\text{V}, V_{DS}=15\text{V}, I_D=13.7\text{A}$		30.5	36	nC
Q_{gs}	Gate Source Charge			4.6		nC
Q_{gd}	Gate Drain Charge			8.6		nC
$t_{\text{D(on)}}$	Turn-On DelayTime	$V_{GS}=10\text{V}, V_{DS}=15\text{V}, R_L=1.1\Omega, R_{\text{GEN}}=3\Omega$		5.5	9	ns
t_r	Turn-On Rise Time			3.4	7	ns
$t_{\text{D(off)}}$	Turn-Off DelayTime			49.8	75	ns
t_f	Turn-Off Fall Time			5.9	11	ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=13.7\text{A}, dI/dt=100\text{A}/\mu\text{s}$		22.5	28	ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=13.7\text{A}, dI/dt=100\text{A}/\mu\text{s}$		12.5	16	nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design.

B: Repetitive rating, pulse width limited by junction temperature.

C. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and lead to ambient.

D. The static characteristics in Figures 1 to 6 are obtained using <300 μs pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The SOA curve provides a single pulse rating.

F. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.

Rev 1 : Nov. 2010

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

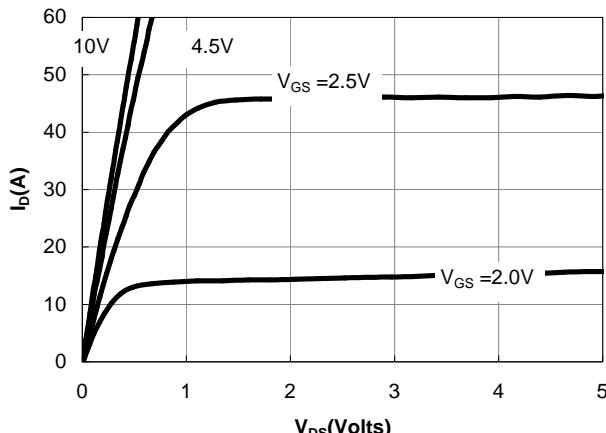


Figure 1: On-Regions Characteristics

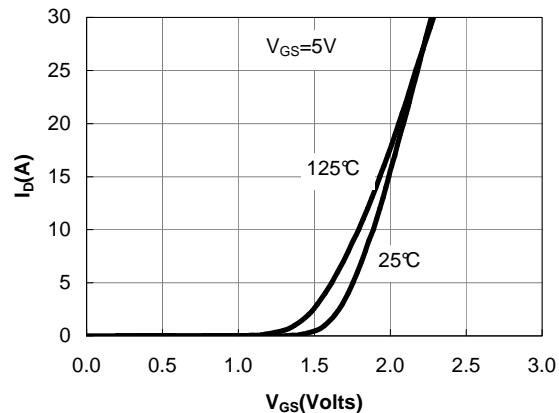


Figure 2: Transfer Characteristics

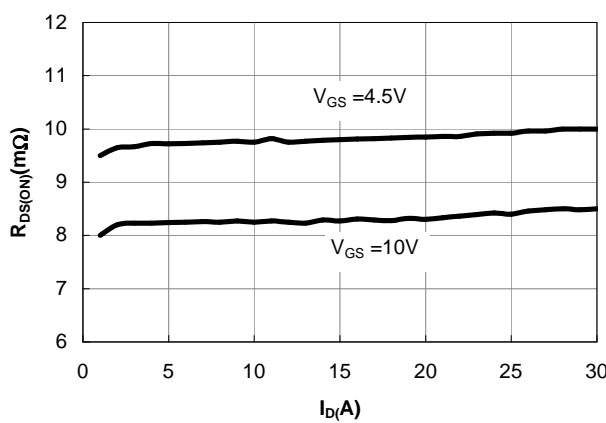


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

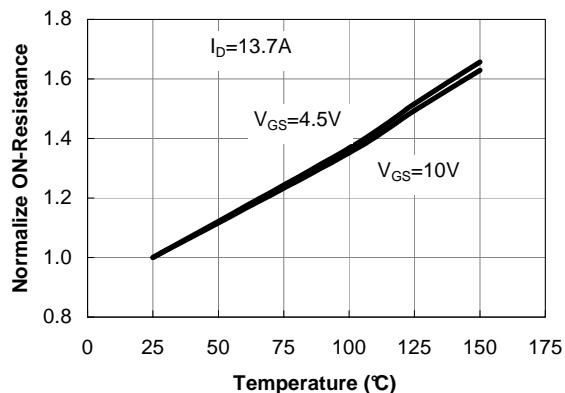


Figure 4: On-Resistance vs. Junction Temperature

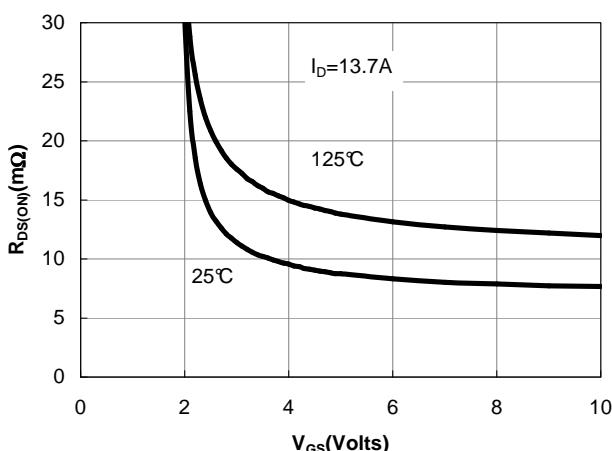


Figure 5: On-Resistance vs. Gate-Source Voltage

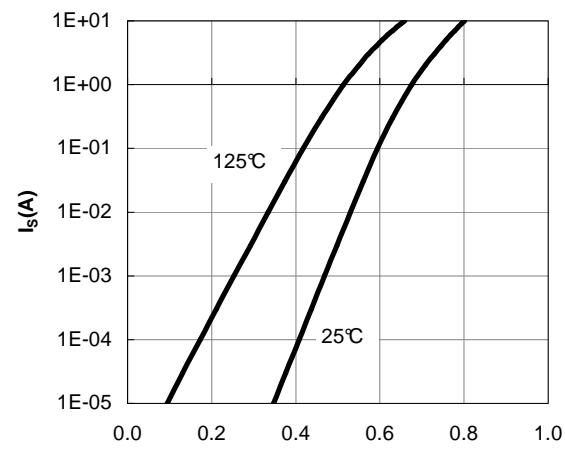
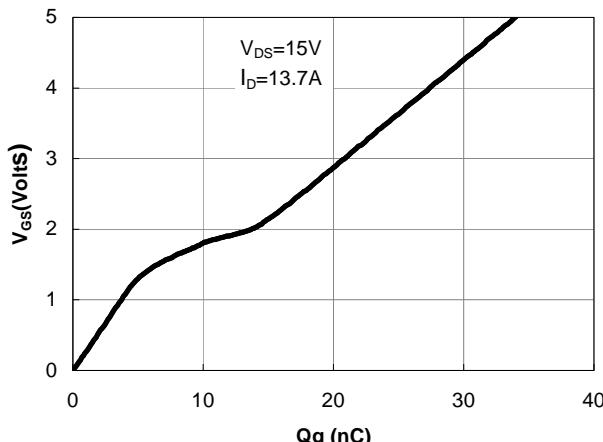
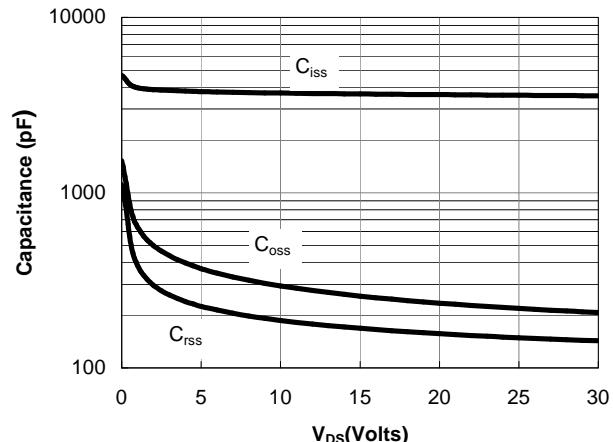
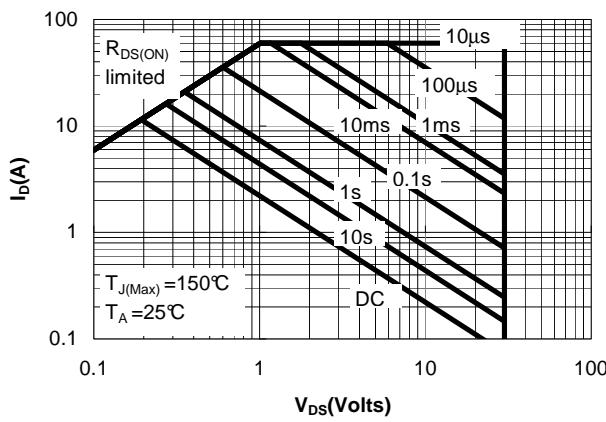
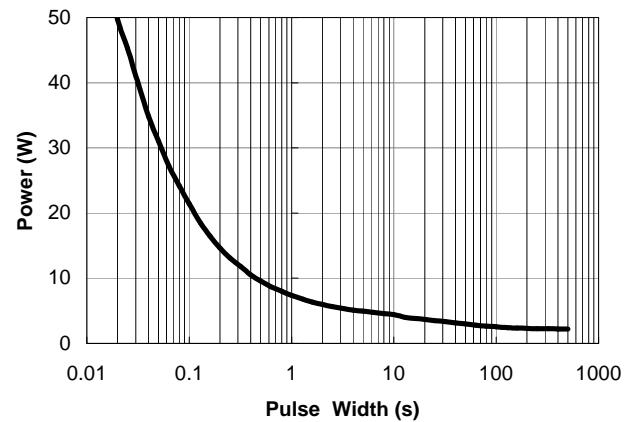
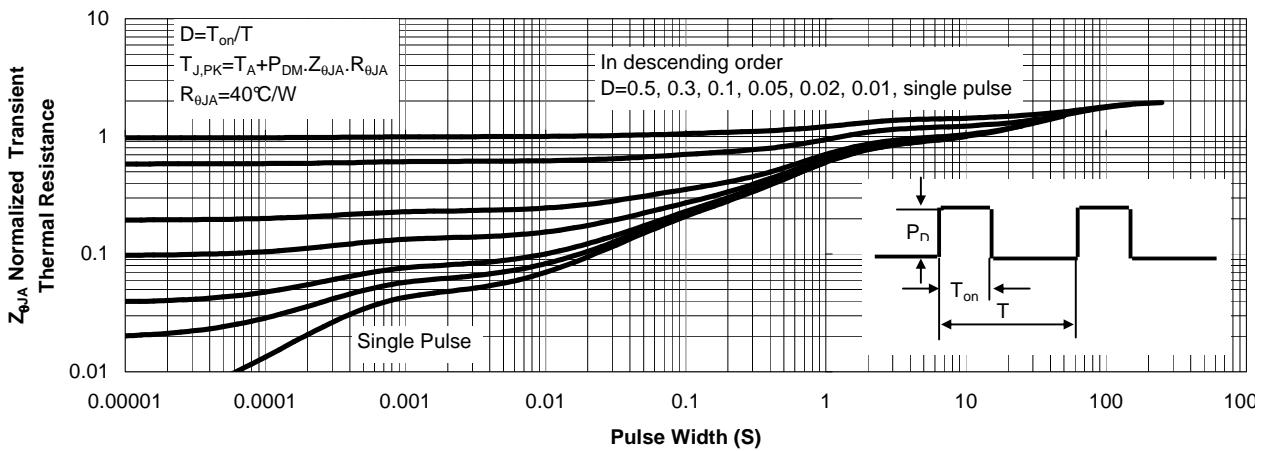


Figure 6: Body-Diode Characteristics

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Figure 7: Gate-Charge Characteristics

Figure 8: Capacitance Characteristics

Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

Figure 11: Normalized Maximum Transient Thermal Impedance